





#### **DUAL SURFACE MOUNT LOW LEAKAGE DIODE**

#### **Features**

- Surface Mount Package Ideally Suited for Automated Insertion
- Suitable for ultra-low leakage current applications, including high-precision instrumentation and portable electronics
- Lead Free By Design/RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Notes 2 & 3)
- Qualified to AEC-Q101 Standards for High Reliability

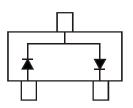
#### **Mechanical Data**

- Case: SOT323
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Finish annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.006 grams (approximate)





Top View



Top View Internal Schematic

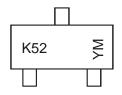
## Ordering Information (Notes 4 & 5)

Part Number	Case	Packaging
BAV199W-7	SOT323	3,000/Tape & Reel

Notes:

- 1. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead.
- 2. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 3. Diodes Inc.`s "Green" Policy can be found on our website at http://www.diodes.com
- 4. For packaging details, go to our website at http://www.diodes.com.
- 5. Product manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

# **Marking Information**



K52= Product Type Marking Code YM = Date Code Marking Y = Year (ex: Z = 2012)M = Month (ex: 9 = September)

Date Code Key

Year	2004	20	05		2012	20	13	2014	2015	20	16	2017
Code	R	,	3		Z		4	В	С	[	)	Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>R</sub> WM	85	V	
RMS Reverse Voltage	V <sub>R(RMS)</sub>	60	V	
Forward Continuous Current (Note 6) Single diode Double diode		I <sub>FM</sub>	160 140	mA
Repetitive Peak Forward Current (Note 6)		I <sub>FRM</sub>	500	mA
Non-Repetitive Peak Forward Surge Current	@ t = 1.0μs @ t = 1.0ms @ t = 1.0s	I <sub>FSM</sub>	4.0 1.0 0.5	A

# **Thermal Characteristics**

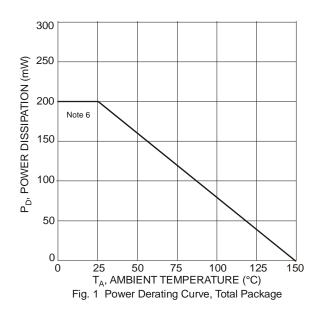
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	$P_{D}$	200	mW
Thermal Resistance Junction to Ambient Air (Note 6)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

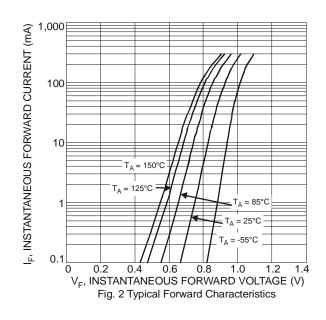
## Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	85	_		V	$I_R = 100 \mu A$
Forward Voltage	V <sub>F</sub>	_		0.90 1.0 1.1 1.25	<b>V</b>	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 50mA I <sub>F</sub> = 150mA
Leakage Current (Note 7)	I <sub>R</sub>	_	_	5.0 80	nA nA	$V_R = 75V$ $V_R = 75V$ , $T_J = 150$ °C
Total Capacitance	C <sub>T</sub>	_	2		рF	$V_R = 0$ , $f = 1.0MHz$
Reverse Recovery Time	t <sub>rr</sub>	_	_	3.0	μS	$I_F = I_R = 10 \text{mA},$ $I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$

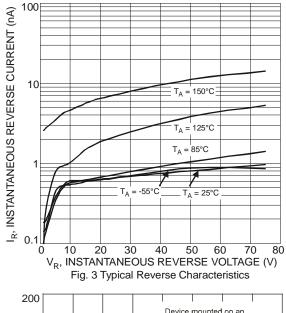
Notes:

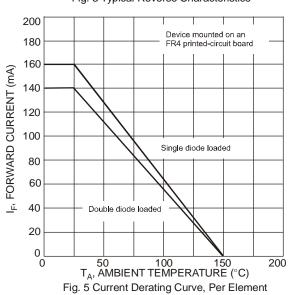
- 6. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com. 7. Short duration pulse test used to minimize self-heating effect.

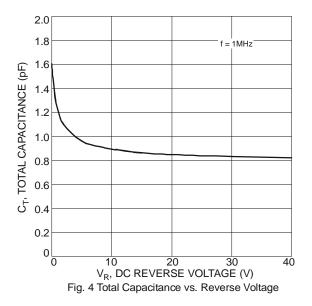




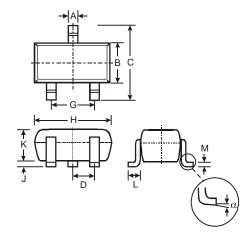








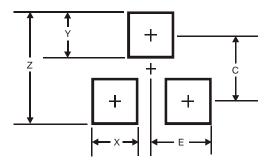
# **Package Outline Dimensions**



SOT323							
Dim	Min	Max	Тур				
Α	0.25	0.40	0.30				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D	-	-	0.65				
G	1.20	1.40	1.30				
Н	1.80	2.20	2.15				
J	0.0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
M	0.10	0.18	0.11				
α	0°	8°	-				
All	All Dimensions in mm						



### Suggested Pad Layout



Dimensions	Value (in mm)			
Z	2.8			
Х	0.7			
Υ	0.9			
С	1.9			
E	1.0			

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>>Diodes Incorporated(达迩科技(美台))